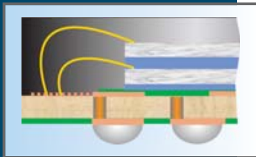
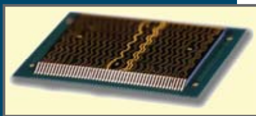
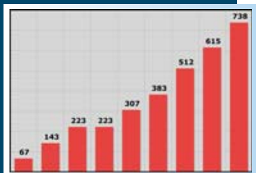
Advanced Packaging Update:
Market and Technology Trends

Vol. 4-009







Volume 4 of the Advanced Packaging Update features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe substrates. Unit growth projections are also provided for stacked die CSP and package-on-package (PoP) shipments. Shipments of package-in-package (PiP) are also included. The market for each package type is based on input from both captive and merchant assembly operations. Key applications and drivers for unit volume growth are highlighted. An economic analysis examines macroeconomic trends and the impact on the semiconductor packaging and assembly industry. A special section is devoted to an examination of alternatives to through silicon via (TSV). The section includes Proximity Computing, developed by Sun Microsystems (now owned by Oracle), stacking technology from Vertical Circuits and 3D Plus, and the deep silicon via technology developed by Jazz Semiconductor (now TowerJazz).

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